Die Metal oxide Lead Dioxide (PbO2) 1309-600 0 2.63 0.09 Composition Sillorn (S) 7440-21-3 0.16 97.37 3.21 Solder Wire Tin alloy Tin (Sn) 7440-21-5 0.01 10.0 0.21 Solder Wire Silver alloy Silver (Ag) 7440-22-4 0.0 2.0 0.04 Lead alloy Lead (Pb) 7439-92-1 0.09 88.0 1.86 Wire Pure metal Aluminium (Al) 7429-90-5 0.4 100.0 8.16 Lead Frame Iron-nickel alloy Phosphorous (P) 7723-140 0.4 100.0 8.16 Lead Frame Iron-nickel alloy Nickel (Ni) - cas no. 7440-02-0 7440-92-0 0.73 1.08 1.386 Post-plating Pure metal Tin (Sn) 7440-92-0 9.9 9.9 1.374-62 Post-plating Pure metal Tin (Sn) 7440-91-5 1.02 100.0 2.08 Mould Polymer Phenol Formaldehyde resin (ge	External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Solder Wire Tin alloy Tin (Sn) 7440-31-5 0.01 10.0 0.21 Solder Wire Tin alloy Tin (Sn) 7440-31-5 0.01 10.0 0.21 Lead alloy Silver (Ag) 7440-22-4 0 2.0 0.04 Lead alloy Lead (Pb) 7439-92-1 0.09 88.0 1.86 Wire Pure metal Aluminium (Al) 7429-90-5 0.4 100.0 8.16 Lead Frame Iron-nickel alloy Phosphorous (P) 7723-14-0 0.02 0.03 0.41 Lead Frame Iron-nickel alloy Nickel (NI) - cas no. 7440-02-0 7440-02-0 0.73 1.08 14.86 Lead Frame Iron-nickel alloy Copper (Cu) 7440-50-8 66-92 98.79 1359.35 Lead Frame Pure metal Tin (Sn) 7440-50-8 66-92 98.79 1374-62 Post-plating Pure metal Tin (Sn) 7440-51-5 1.02 100.0 20.68 Mould Compound Polymer P	Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0	2.63	0.09
Solder Wire Tin alloy Tin (Sn) 7440-31-5 0.01 10.0 0.21 Image: Silver alloy Silver (Ag) 7440-22-4 0 2.0 0.04 Lead alloy Lead (Pb) 7439-92-1 0.09 88.0 1.86 Wire Pure metal Aluminium (Al) 7429-90-5 0.4 100.0 8.16 Lead Frame Iron-nickel alloy Phosphorous (P) 7723-14-0 0.02 0.03 0.41 Lead Frame Iron-nickel alloy Nickel (Ni) - cas no. 7440-02-0 7440-02-0 0.73 1.08 14.86 Post-plating Iron-nickel alloy Copper (Cu) 7440-50-8 66.92 98.79 1359.35 Post-plating Pure metal Tin (Sn) 7440-50-8 66.92 98.79 1374.62 Post-plating Pure metal Tin (Sn) 7440-50-8 66.92 98.79 1374.62 Post-plating Pure metal Tin (Sn) 7440-50-8 1.02 100.0 20.68 Mould Compound Polymer		Doped silicon	Silicon (Si)	7440-21-3	0.16	97.37	3.21
Silver alloy Silver (Ag) 7440-22-4 0 2.0 0.04				Subtotal	0.16	100	3.3
Lead alloy Lead (Pb) 7439-92-1 0.09 88.0 1.86	Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.01	10.0	0.21
Wire Pure metal Aluminium (AI) 7429-90-5 0.4 100.0 8.16 Lead Frame Iron-nickel alloy Phosphorous (P) 7723-14-0 0.02 0.03 0.41 Lead Frame Iron-nickel alloy Nickel (NI)- cas no. 7440-02-0 7440-02-0 0.73 1.08 14.86 Post-plating Pure metal Tin (Sn) 7440-50-8 66.92 98.79 1374-62 Post-plating Pure metal Tin (Sn) 7440-31-5 1.02 100.0 20.68 Mould Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 1.38 4.5 27.95 Medal Metal Metal Metal hydroxide Metal hydroxide 60676-86-0 22.93 75.0 465.75 Metal hydroxide Metal hydroxide 1333-86-4 0.15 0.5 3.1 Carbon Black Carbon black Carbon black 1333-86-4 0.15 0.5 3.1		Silver alloy	Silver (Ag)	7440-22-4	0	2.0	0.04
Wire Pure metal Aluminium (Al) 7429-90-5 0.4 100.0 8.16 Lead Frame Iron-nickel alloy Phosphorous (P) 7723-14-0 0.02 0.03 0.41 Lead Frame Iron-nickel alloy Nickel (Ni) - cas no. 7440-02-0 7440-02-0 0.73 1.08 14.86 Iron-nickel alloy Copper (Cu) 7440-50-8 66.92 98.79 1374.62 Post-plating Pure metal Tin (Sn) 7440-31-5 1.02 100.0 20.68 Mould Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 1.38 4.5 27.95 Mould Compound Polymer Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) 25928-94-3 3.06 10.0 62.1 Mould Pydroxide Metal hydroxide 60676-86-0 22.93 75.0 465.75 Lead Pydroxide Metal hydroxide 1333-86-4 0.15 0.5 3.1 Lead Pydroxide Carbon Black Carbon black 1333-86-4 0.15 0.5 3.1		Lead alloy	Lead (Pb)	7439-92-1	0.09	88.0	1.86
Lead Frame Iron-nickel alloy Phosphorous (P) 7723-14-0 0.02 0.03 0.41				Subtotal	0.1	100	2.11
Lead Frame Iron-nickel alloy Phosphorous (P) 7723-14-0 0.02 0.03 0.41 Iron-nickel alloy Nickel (Ni) - cas no. 7440-02-0 7440-02-0 0.73 1.08 14.86 Iron-nickel alloy Copper (Cu) 7440-50-8 66.92 98.79 1359.35 Post-plating Pure metal Tin (Sn) 7440-31-5 1.02 100.0 20.68 Mould Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 1.38 4.5 27.95 Filler Silica fused 60676-86-0 22.93 75.0 465.75 Metal hydroxide Metal hydroxide 1333-86-4 0.15 0.5 3.1 Carbon Black Carbon black Carbon black 1333-86-4 0.15 0.5 3.1	Wire	Pure metal	Aluminium (AI)	7429-90-5	0.4	100.0	8.16
				Subtotal	0.4	100	8.16
Add	Lead Frame		Phosphorous (P)	7723-14-0	0.02	0.03	0.41
Subtotal Filler Silica fused Subtotal Subtota			Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.73	1.08	14.86
Post-plating Pure metal Tin (Sn) 7440-31-5 1.02 100.0 20.68 Mould Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 1.38 4.5 27.95 Polymer Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) 25928-94-3 3.06 10.0 62.1 Metal hydroxide Metal hydroxide 1333-86-4 0.15 0.5 3.1 Subtotal Subtotal 30.58 100 621			Copper (Cu)	7440-50-8	66.92	98.79	1359.35
Mould Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 1.38 4.5 27.95 Polymer Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) 25928-94-3 3.06 10.0 62.1 Filler Silica fused 60676-86-0 22.93 75.0 465.75 Metal hydroxide Metal hydroxide 3.06 10.0 62.1 Carbon Black Carbon black 1333-86-4 0.15 0.5 3.1 Subtotal 30.58 100 621				Subtotal	67.67	99.9	1374.62
Mould Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 1.38 4.5 27.95 Polymer Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) 25928-94-3 3.06 10.0 62.1 Filler Silica fused 60676-86-0 22.93 75.0 465.75 Metal hydroxide Metal hydroxide 1333-86-4 0.15 0.5 3.1 Carbon Black Carbon black Subtotal 30.58 100 621	Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.02	100.0	20.68
Compound Polymer Phenol Formaldehyde resin (generic) 9003-35-4 1.38 4.5 27.95 Polymer Epichlorohydrin/Diethyleneglycol Epoxy resin (generic) 25928-94-3 3.06 10.0 62.1 Filler Silica fused 60676-86-0 22.93 75.0 465.75 Metal hydroxide Metal hydroxide 3.06 10.0 62.1 Carbon Black Carbon black 1333-86-4 0.15 0.5 3.1 Subtotal 30.58 100 621				Subtotal	1.02	100	20.68
Filler Silica fused 60676-86-0 22.93 75.0 465.75 Metal hydroxide Metal hydroxide 3.06 10.0 62.1 Carbon Black Carbon black 1333-86-4 0.15 0.5 3.1 Subtotal 30.58 100 62.1		Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.38	4.5	27.95
Metal hydroxide 3.06 10.0 62.1 Carbon Black Carbon black 1333-86-4 0.15 0.5 3.1 Subtotal 30.58 100 621		Polymer		25928-94-3	3.06	10.0	62.1
hydroxide Metal hydroxide 3.06 10.0 62.1 Carbon Black Carbon black 1333-86-4 0.15 0.5 3.1 Subtotal 30.58 100 621		Filler	Silica fused	60676-86-0	22.93	75.0	465.75
Subtotal 30.58 100 621			Metal hydroxide		3.06	10.0	62.1
		Carbon Black	Carbon black	1333-86-4	0.15	0.5	3.1
Total 99.93 100 2029.87				Subtotal	30.58	100	621
				Total	99.93	100	2029.87

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